



(0.635 mm) .025"



DED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFSS

Insulator Material: Liquid Crystal Polymer Contact, Ground Plane & Shield Material: Phosphor Bronze

Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane tails)

Voltage Rating:
300 VAC mated with QMSS
Operating Temp:
-55 °C to +125 °C

RoHS Compliant:

PROCESSING

Lead-Free Solderable:

Yes SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) **Board Stacking:**

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

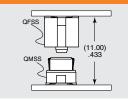
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

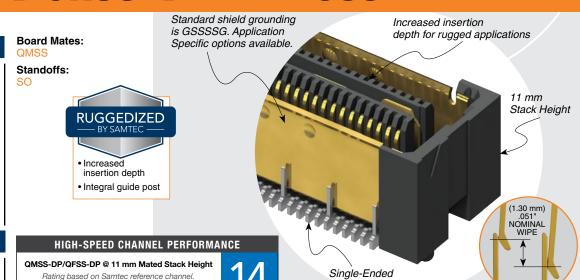
- · Headers without Alignment Pins
- 8 Power Pins/End
- · 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- · Guide Holes
- 64 (-DP) and 104 pins per row Contact Samtec.

APPLICATION



Notes: Patented

Some lengths, styles and options are non-standard, non-returnable.



For full SI performance data visit Samtec.com or contact SIG@samtec.com

-026, -052, -078 (52 total pins per bank 40 signals + 12 grounds to shield = -D)

PINS PER ROW

NO. OF PAIRS

–016, –032, –048 (16 pairs per bank = -D-DP)

No. of Banks x (21.34) .840 + (1.02) .040 → **←**(2.10) .083 -(21.34) .840 (8.13).320 (0.23) 01 .009

(0.89) (7.06).278 (1.02) .040 DIA → -D -D-DP (2.54) ← (2.00) .07874 No. of Banks x (21.34) .840 + (12.87) .507

-PC4 OPTION

= 10 μ" (0.25 μm) Gold on Signal Pins, Shield and **Ground Plane** (Tin on Signal Pin tails, and Ground Plane tails)

PLATING

OPTION

Signal routing

−D = Single-Ended -D-DP = Differential Pair

(0.10)

.004

.070

-PC4 = 4 Power Pins/End (N/A with -A)

OTHER

OPTION

OTHER SOLUTIONS



See SO Series for precision machined standoffs.

Due to technical progress, all designs, specifications and components are subject to change without notice WWW.SAMTEC.COM